

MC21605GB6W1-FPTLW	2 x 16	5mm Character Height	LCD Module
Specification			
Version: 1		Date: 27/11/2011	
Revision			
1	25/11/2011	First issue	

Display Features			
Character Count	2 x 16		
Appearance	Black on White		
Logic Voltage	5V		
Interface	Parallel		
Font Set	English / Japanese		
Display Mode	Transflective		
Character Height	5.55mm		
LC Type	FSTN		
Module Size	80.00 x 36.00 x 13.50mm		
Operating Temperature	-20°C ~ +70°C		
Construction	COB	Box Quantity	Weight / Display
LED Backlight	White	~	~

* - For full design functionality, please use this specification in conjunction with the ST7066U specification. (Provided Separately)

Display Accessories	
Part Number	Description
MCCMDB-16SIL	LCD Interconnect board, can be driven from either a PC or a single Board computer with a USB output.
MCCBL1A16SLIP-16DILS-150	16 Way, Single in-line to Dual In-line connector Cable.
MCCBL1A16SLIP-16SILS-150	16 Way, Single in-line to Single In-line connector Cable.

Optional Variants		
Fonts	Appearances	Voltage
English/Euro English/Cyrillic	Black on Yellow/ Green White on Blue Black on RGB	3V 3.3V



General Specification

The Features is described as follow:

- Module dimension: 80.0 x 36.0 x 13.5 (max.) mm³
- View area: 66.0 x 16.0 mm²
- Active area: 56.20 x 11.5 mm²
- Number of Characters: 16 characters x 2 Lines
- Dot size: 0.55 x 0.65 mm²
- Dot pitch: 0.60 x 0.70 mm²
- Character size: 2.95 x 5.55 mm²
- Character pitch: 3.55 x 5.95 mm²
- LCD type: FSTN Positive Transflective
- Duty: 1/16
- View direction: 6 o'clock
- Backlight Type: LED, White

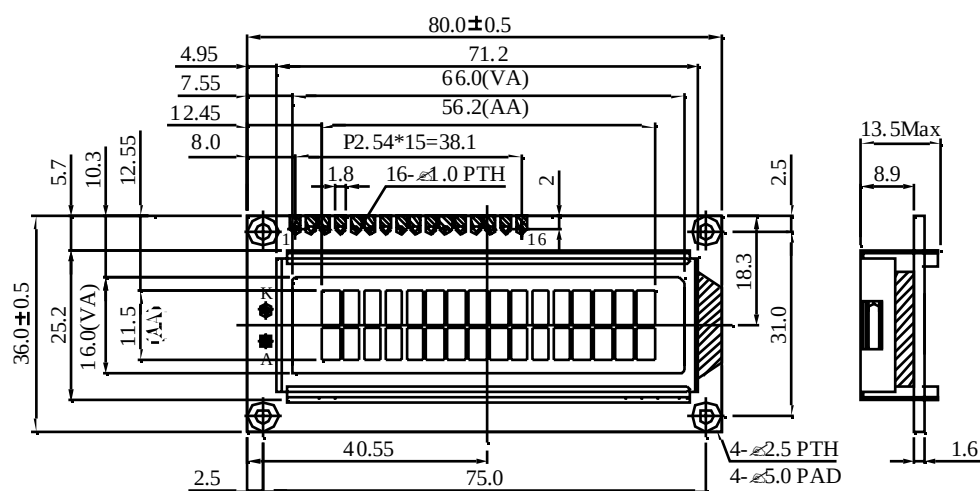
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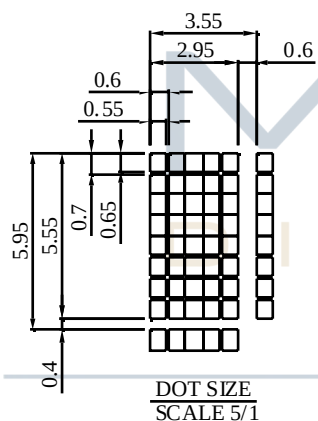
Interface Pin Function

Pin #	Symbol	Level	Description
1	V _{SS}	0V	Ground
2	V _{DD}	5.0V	Supply Voltage for logic
3	VO	(Variable)	Operating voltage for LCD
4	RS	H/L	H: DATA, L: Instruction code
5	R/W	H/L	H: Read(MPU→Module) L: Write(MPU→Module)
6	E	H,H→L	Chip enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	K	—	LED —
16	A	—	LED +

Outline Dimension & Block Diagram

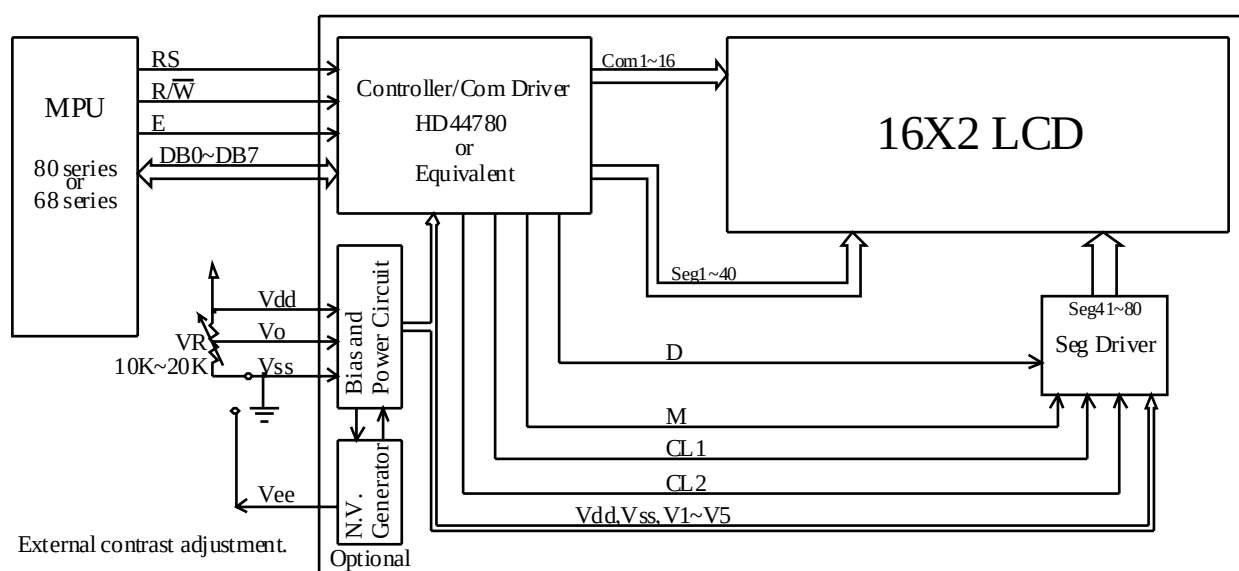


PIN NO	SYMBOL
1	V _{ss}
2	V _{dd}
3	V _o
4	RS
5	R/ $\overline{W}$
6	E
7	DB0
8	DB1
9	DB2
10	DB3
11	DB4
12	DB5
13	DB6
14	DB7
15	K
16	A



SCALE 3/1

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Function Description

The LCD display Module is built in a LSI controller, the controller has two 8-bit registers, an instruction register (IR) and a data register (DR).

The IR stores instruction codes, such as display clear and cursor shift, and address information for display data RAM (DDRAM) and character generator (CGRAM). The IR can only be written from the MPU. The DR temporarily stores data to be written or read from DDRAM or CGRAM. When address information is written into the IR, then data is stored into the DR from DDRAM or CGRAM. By the register selector (RS) signal, these two registers can be selected.

RS	R/W	Operation
0	0	IR write as an internal operation (display clear, etc.)
0	1	Read busy flag (DB7) and address counter (DB0 to DB7)
1	0	Write data to DDRAM or CGRAM (DR to DDRAM or CGRAM)
1	1	Read data from DDRAM or CGRAM (DDRAM or CGRAM to DR)

Busy Flag (BF)

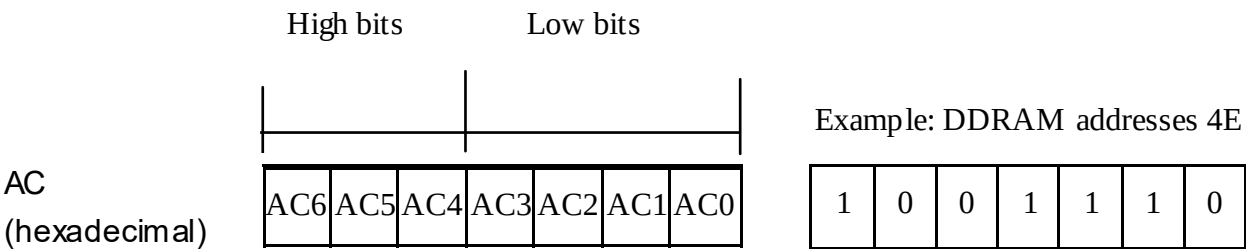
When the busy flag is 1, the controller LSI is in the internal operation mode, and the next instruction will not be accepted. When RS=0 and R/W=1, the busy flag is output to DB7. The next instruction must be written after ensuring that the busy flag is 0.

Address Counter (AC)

The address counter (AC) assigns addresses to both DDRAM and CGRAM.

Display Data RAM (DDRAM)

This DDRAM is used to store the display data represented in 8-bit character codes. Its extended capacity is 80×8 bits or 80 characters. Below figure is the relationships between DDRAM addresses and positions on the liquid crystal display.



Display position DDRAM address

1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16

00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F
40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F

2-Line by 16-Character Display

Character Generator ROM (CGROM)

The CGROM generate 5×8 dot or 5×10 dot character patterns from 8-bit character codes. See Table 2.

Character Generator RAM (CGRAM)

In CGRAM, the user can rewrite character by program. For 5×8 dots, eight character patterns can be written, and for 5×10 dots, four character patterns can be written.

Write into DDRAM the character code at the addresses shown as the left column of table 1.

To show the character patterns stored in CGRAM.

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Relationship between CGRAM Addresses, Character Codes (DDRAM) and Character patterns.

Table 1.

For 5 * 8 dot character patterns

Character Codes (DDRAM data)								CGRAM Address								Character Patterns (CGRAM data)								
7	6	5	4	3	2	1	0		5	4	3	2	1	0	7	6	5	4	3	2	1	0		
High				Low					High				Low				High				Low			
0 0 0 0 * 0 0 0								0 0 0		0	0	0		*	*	*				0	Character pattern(1)			
										0	0	1		*	*	*		0	0	0				
										0	1	0		*	*	*		0	0	0				
										0	1	1		*	*	*						0		
										1	0	0		*	*	*		0				0	0	
										1	0	1		*	*	*		0	0			0		
										1	1	0		*	*	*		0	0	0				
										1	1	1		*	*	*		0	0	0		0	0	
										0	0	0		*	*	*			0	0		0		
										0	0	1		*	*	*		0				0		
0 0 0 0 * 0 0 1								0 0 1		0	1	0		*	*	*		0	0		Character pattern(2)			
										1	0	0		*	*	*		0	0			0	0	
										1	0	1		*	*	*		0	0			0	0	
										1	1	0		*	*	*		0	0			0	0	
										1	1	1		*	*	*		0	0	0		0	0	
										0	0	0		*	*	*								
										0	0	0		*	*	*							Cursor pattern	
										0	0	1		*	*	*								
0 0 0 0 * 1 1 1									1 1 1	1	0	0												
										1	0	1												
										1	1	0												
										1	1	1		*	*	*								

For 5 * 10 dot character patterns

Character Codes (DDRAM data)								CGRAM Address								Character Patterns (CGRAM data)															
7	6	5	4	3	2	1	0	5				4				3				2				1				0			
High				Low				High				Low				High				Low											
0 0 0 0 * 0 0 0								0 0				0	0	0	0	*	*	*	0	0	0	0	0	0	0	0	0	0			
												0	0	0	1	*	*	*	0	0	0	0	0	0	0	0					
												0	0	1	0	*	*	*	0	0	0	0	0	0	0	0					
												0	0	1	1	*	*	*	0	0	0	0	0	0	0	0					
												0	1	0	0	*	*	*	0	0	0	0	0	0	0	0					
												0	1	0	1	*	*	*	0	0	0	0	0	0	0	0					
												0	1	1	0	*	*	*	0	0	0	0	0	0	0	0					
												0	1	1	1	*	*	*	0	0	0	0	0	0	0	0					
												1	0	0	0	*	*	*	0	0	0	0	0	0	0	0	0				
												1	0	0	1	*	*	*	0	0	0	0	0	0	0	0	0				
												1	0	1	0	*	*	*	0	0	0	0	0	0							

■ : " High "

Character Generator ROM Pattern

Table.2

Upper 4 bit Lower 4 bit		LLLL	LL LH	LL HL	LL HH	LH LL	LH LH	LH HL	LH HH	HL LL	HL LH	HL HL	HL HH	HH LL	HH LH	HH HL	HH HH
LLLL	CG RAM (1)	±		00P	'	r	S	E	a	'	r	A	B	c			
LL LH	CG RAM (2)	≡	!	1A	Q	a	7	Q	a	1	'	J	T	Y	V		
LL HL	CG RAM (3)	7	"	2B	R	b	r	E	B	a	'	w	S	E	Q		
LL HH	CG RAM (4)	2	#	3C	S	c	3	B	E	a	'	P	M	E	W		
LH LL	CG RAM (5)	7	\$	4D	T	d	t	a	S	C	'	a	r	Z	Q		
LH LH	CG RAM (6)	2	%	5E	U	e	U	a	B	E	'	a	T	a	n	"	
LH HL	CG RAM (7)	7	&	6F	V	f	v	a	C	R	'	W	4	E	B		
LH HH	CG RAM (8)	2	'	7G	W	w	G	C	R	x	'	A	L				
HL LL	CG RAM (1)	2	(	8H	X	x	H	E	S	f	'	E	K	P			
HL LH	CG RAM (2)	2	)	9I	Y	y	I	E	O	1	'	7	M	A	Q		
HL HL	CG RAM (3)	2	*	AJ	Z	z	J	E	O	A	'	7	P				
HL HH	CG RAM (4)	2	+	BK			K	C	R	A	'	S	L	V			
HH LL	CG RAM (5)	≡	=	C	L	l	L	E	R	B	'	U	S	Z	O		
HH LH	CG RAM (6)	2	-	D	M	m	D	E	R	B	'	U	S	Z	O		
HH HL	CG RAM (7)	2	.	E	N	n	E	R	B	O	'	V	B	P	B		
HH HH	CG RAM (8)	2	/	F	O	o	F	E	R	B	'	V	B	P	B		

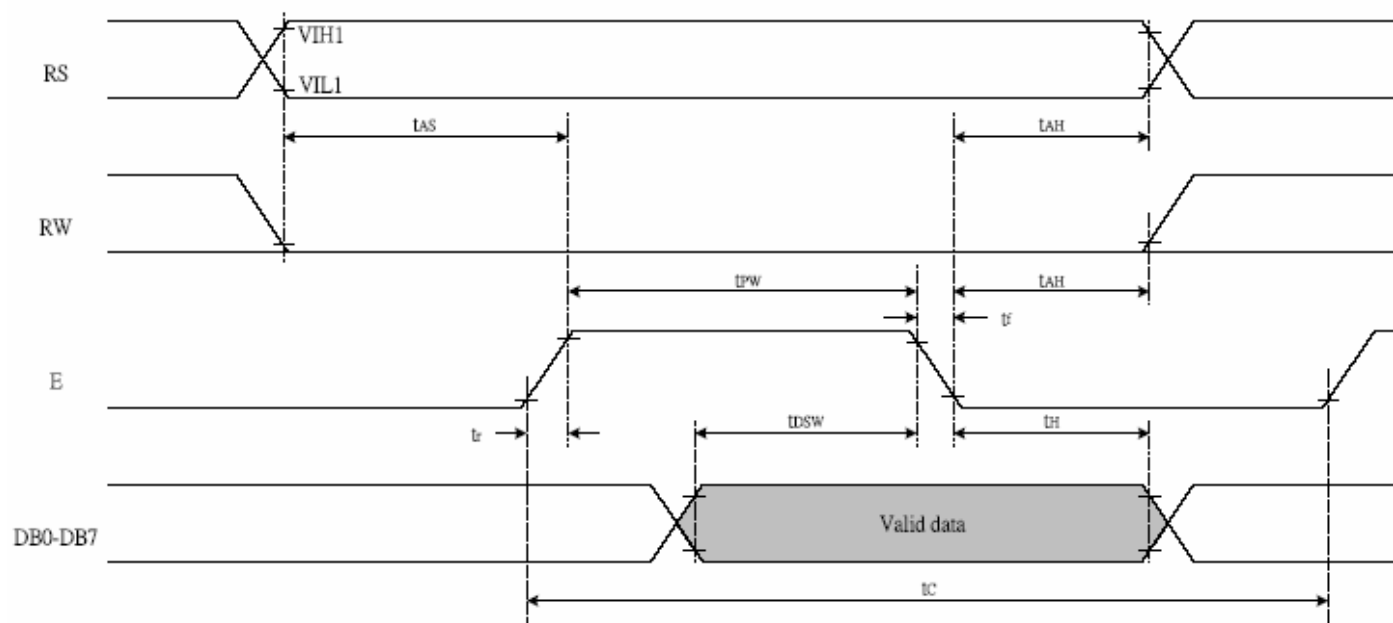
Instruction Table

Instruction	Instruction Code										Description	Execution time (fosc=270Khz)
	RS	RW	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0		
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC	1.52ms
Return Home	0	0	0	0	0	0	0	0	1	—	Set DDRAM address to "00H" from AC and return cursor to its original position if shifted. The contents of DDRAM are not changed.	1.52ms
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	SH	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37μs
Display ON/OFF Control	0	0	0	0	0	0	1	D	C	B	D=1:entire display on C=1:cursor on B=1:cursor position on	37μs
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	—	—	Set cursor moving and display shift control bit, and the direction, without changing DDRAM data.	37μs
Function Set	0	0	0	0	1	DL	N	F	—	—	DL:interface data is 8/4 bits N:number of line is 2/1 F:font size is 5x11/5x8	37μs
Set CGRAM Address	0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0	Set CGRAM address in address counter	37μs
Set DDRAM Address	0	0	1	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Set DDRAM address in address counter	37μs
Read Busy Flag and Address	0	1	BF	AC6	AC5	AC4	AC3	AC2	AC1	AC0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	0μs
Write Data to RAM	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM (DDRAM/CGRAM)	37μs
Read Data from RAM	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM (DDRAM/CGRAM)	37μs

* "—" : don't care

Timing Characteristics

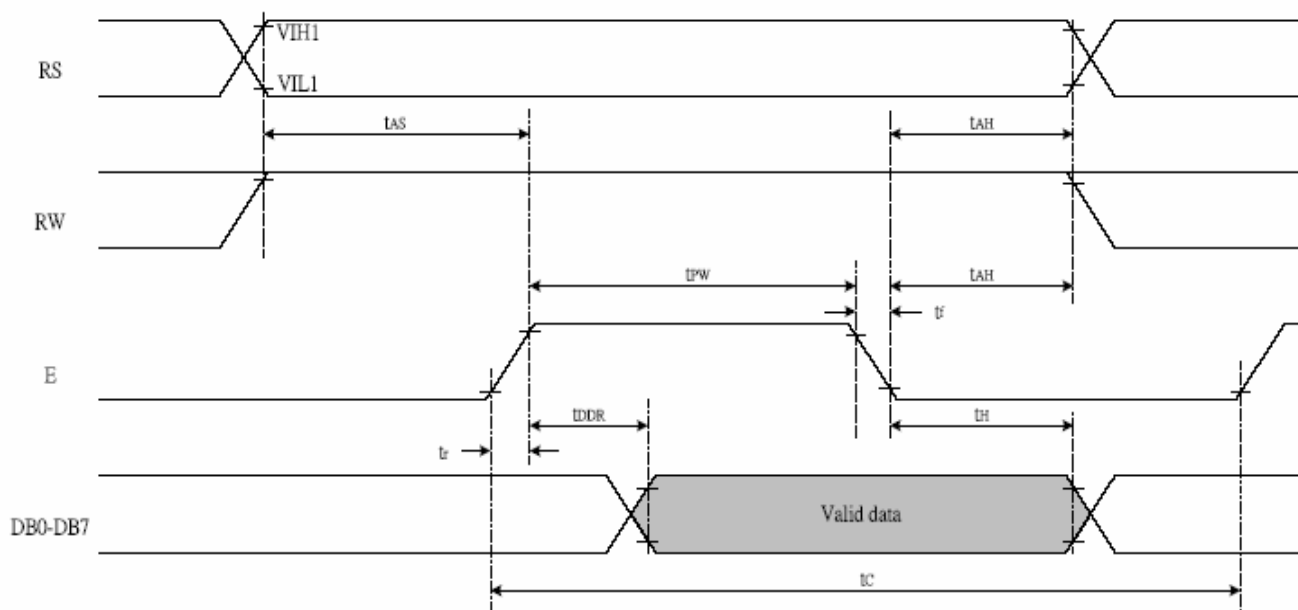
Writing data from MPU to ST7066U



Ta=-30~+85℃, VDD=5.0± 0.5V

TC	Enable Cycle Time	Pin E	1200	-	-	ns
TPW	Enable Pulse Width	Pin E	140	-	-	ns
TR,TF	Enable Rise/Fall Time	Pin E	-	-	25	ns
TAS	Address Setup Time	Pins: RS,RW,E	0	-	-	ns
TAH	Address Hold Time	Pins: RS,RW,E	10	-	-	ns
TDSW	Data Setup Time	Pins: DB0 - DB7	40	-	-	ns
TH	Data Hold Time	Pins: DB0 - DB7	10	-	-	ns

Reading data from ST7066U to MPU

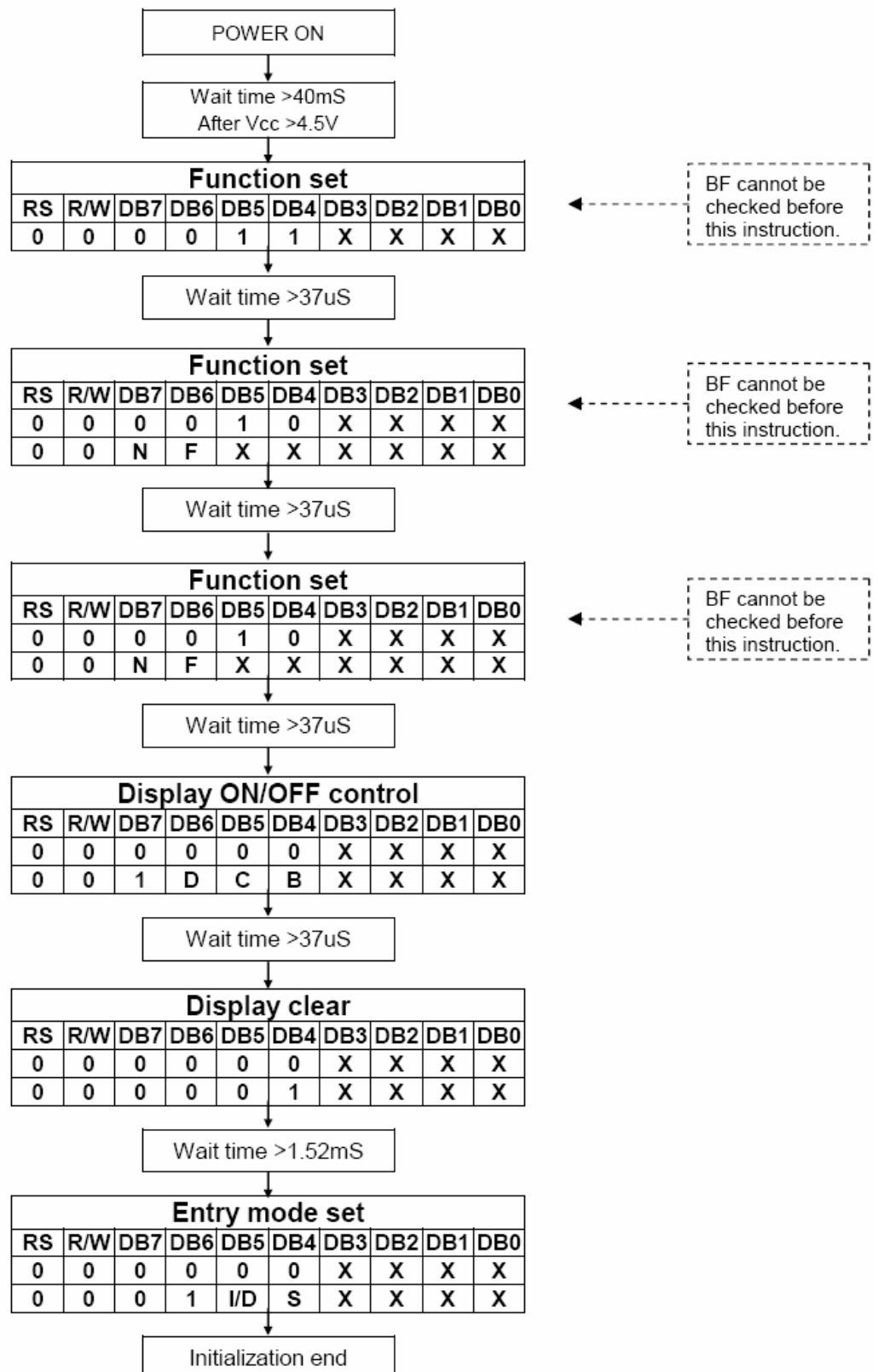


$T_a = -30 \sim +85^{\circ}\text{C}$, $V_{DD} = 5.0 \pm 0.5\text{V}$

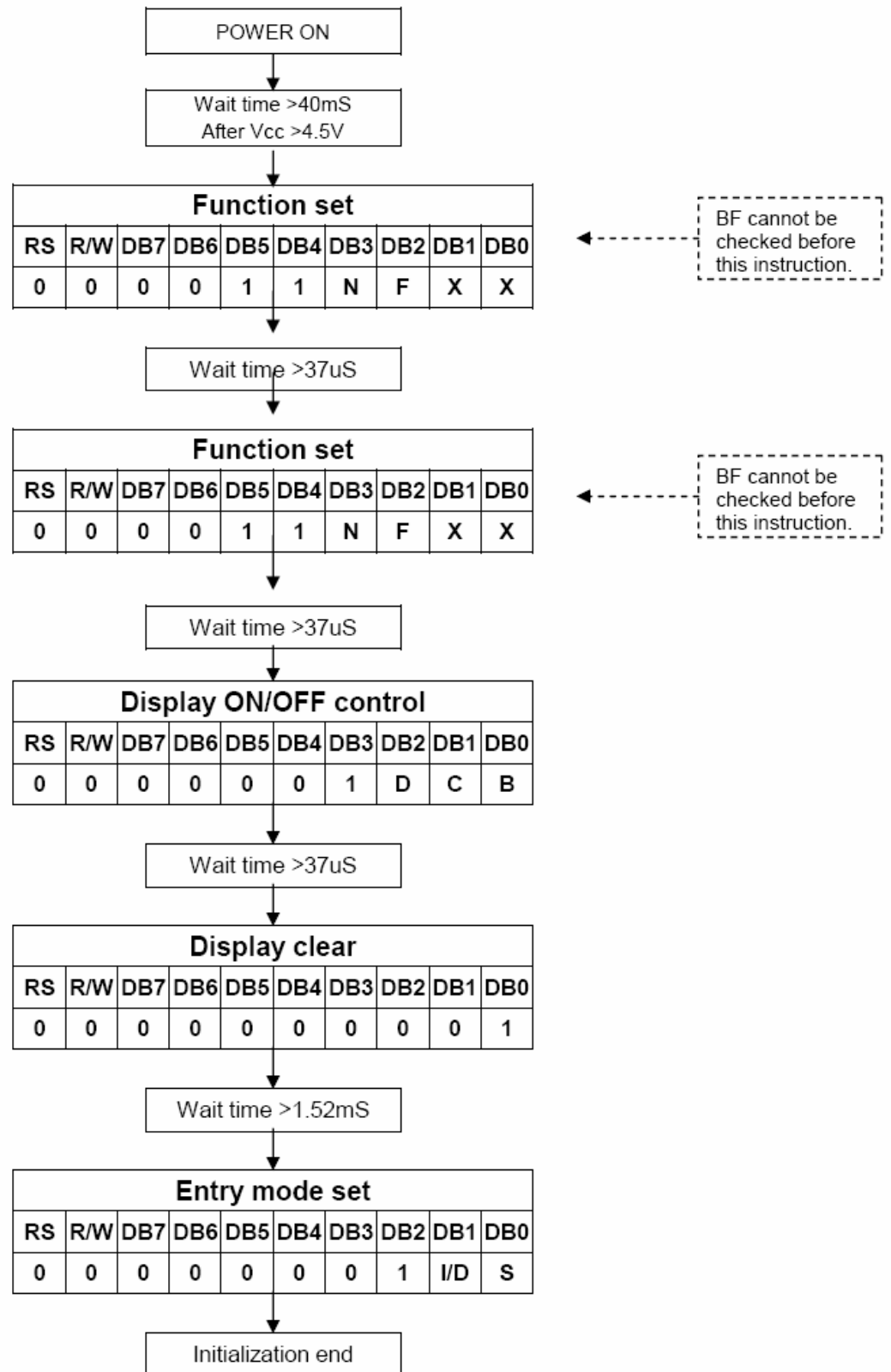
Read Mode (Reading Data from ST7066U to MPU)						
TC	Enable Cycle Time	Pin E	1200	-	-	ns
TPW	Enable Pulse Width	Pin E	140	-	-	ns
TR,TF	Enable Rise/Fall Time	Pin E	-	-	25	ns
TAS	Address Setup Time	Pins: RS,RW,E	0	-	-	ns
TAH	Address Hold Time	Pins: RS,RW,E	10	-	-	ns
TDDR	Data Setup Time	Pins: DB0 - DB7	-	-	100	ns
TH	Data Hold Time	Pins: DB0 - DB7	10	-	-	ns

Initializing of LCM

- 4-bit Interface (fosc=270KHz)



● 8-bit Interface ($f_{osc}=270\text{KHz}$)

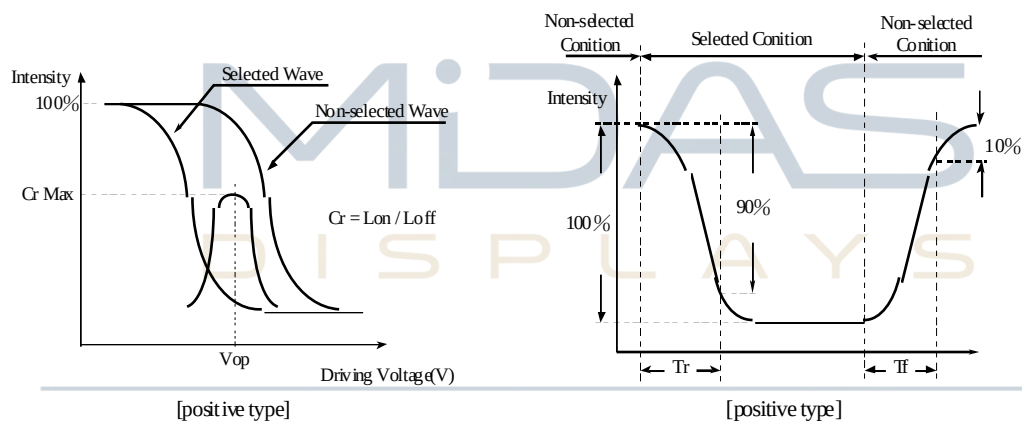


Optical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	(V) θ	$CR \geq 2$	30	—	60	deg
	(H) ϕ	$CR \geq 2$	-45	—	45	deg
Contrast Ratio	CR	—	—	5	—	—
Response Time	T rise	—	—	150	200	ms
	T fall	—	—	150	200	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr , Tf)



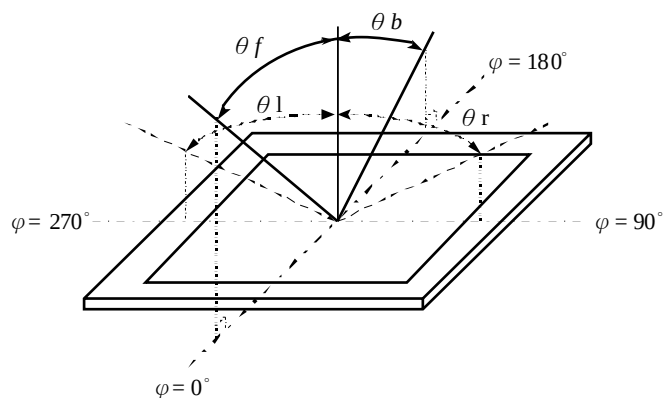
Conditions: DESIGN • MANUFACTURE • SUPPLY

Operating Voltage : Vop

Viewing Angle(θ , ϕ) : 0° , 0°

Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle($CR \geq 2$)



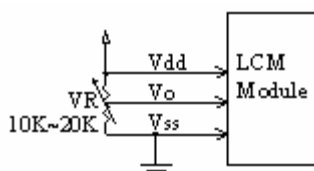
Absolute Maximum Ratings

Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	$^{\circ}\text{C}$
Storage Temperature	T_{ST}	-30	—	+80	$^{\circ}\text{C}$
Input Voltage	V_I	V_{SS}	—	V_{DD}	V
Supply Voltage For Logic	$V_{DD}-V_{SS}$	-0.3	—	7	V
Supply Voltage For LCD	$V_{DD}-V_0$	-0.3	—	13	V

Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	$V_{DD}-V_{SS}$	—	4.5	5.0	5.5	V
Supply Voltage For LCD *Note	$V_{DD}-V_0$	$T_a=-20^{\circ}\text{C}$	—	—	5.2	V
		$T_a=25^{\circ}\text{C}$	—	3.7	—	V
		$T_a=70^{\circ}\text{C}$	3.2	—	—	V
Input High Volt.	V_{IH}	—	$0.7 V_{DD}$	—	V_{DD}	V
Input Low Volt.	V_{IL}	—	V_{SS}	—	0.6	V
Output High Volt.	V_{OH}	—	3.9	—	—	V
Output Low Volt.	V_{OL}	—	—	—	0.4	V
Supply Current	I_{DD}	$V_{DD}=5\text{V}$	1.0	1.2	1.5	mA

* Note: Please design the VOP adjustment circuit on customer's main board



Backlight Information

Specification

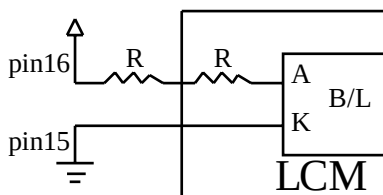
PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	—	32	40	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	—
Reverse Voltage	VR	—	—	5	V	—
Luminous Intensity	IV	400	500	—	CD/M2	ILED=32mA
LED Life Time (For Reference only)	—	—	50K**	—	Hr.	ILED=32mA 25°C ,50-60%RH, (Note 1)
Color	White					

Note : The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1: 50K hours is only an estimate for reference.

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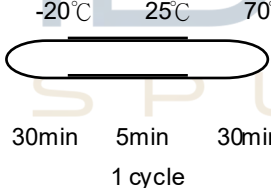
2. Drive from pin15, pin16



(Will never get Vee output from pin15)

Reliability

Content of Reliability Test (wide temperature, -20℃~70℃)

Environmental Test			
Test Item	Content of Test	Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30℃ 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs	-
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60℃,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation 	-20℃/70℃ 10 cycles	-
Vibration test	Endurance test applying the vibration during transportation and using.	fixed amplitude: 15mm Vibration. Frequency: 10~55Hz. One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS= 1.5kΩ CS=100pF 1 time	—

Note1: No dew condensation to be observed.

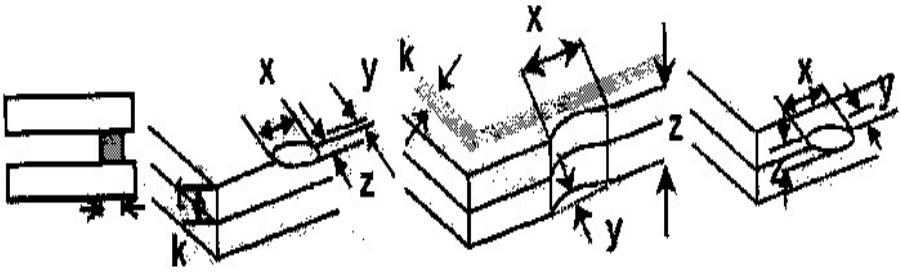
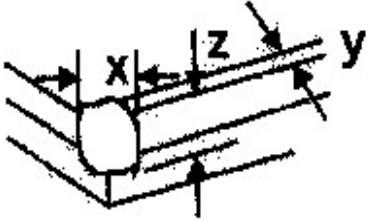
Note2: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after remove from the test chamber.

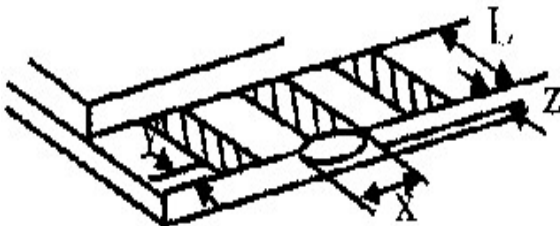
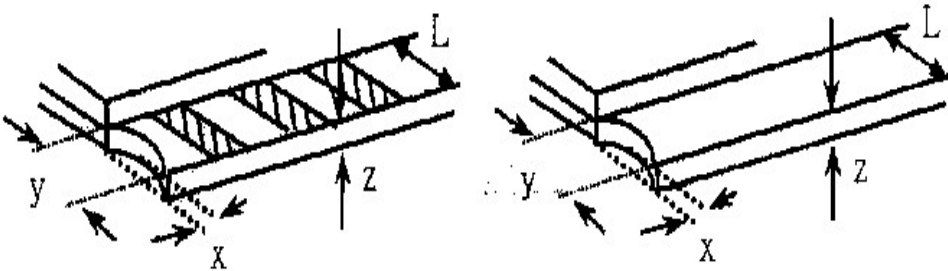
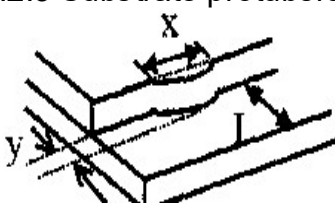
Note3: Vibration test will be conducted to the product itself without putting it in a container.

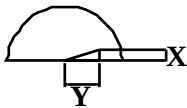
Inspection specification

NO	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65												
02	Black or white spots on LCD (display only)	2.1 White and black spots on display $\leq 0.25\text{mm}$, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm	2.5												
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi=(x+y)/2$	2.5												
		3.2 Line type : (As following drawing)  <table><tr><th>Length</th><th>Width</th><th>Acceptable QTY</th></tr><tr><td>---</td><td>$W\leq 0.02$</td><td>Accept no dense</td></tr><tr><td>$L\leq 3.0$</td><td>$0.02 < W\leq 0.03$</td><td rowspan="2">2</td></tr><tr><td>$L\leq 2.5$</td><td>$0.03 < W\leq 0.05$</td></tr><tr><td>---</td><td>$0.05 < W$</td><td>As round type</td></tr></table>	Length	Width	Acceptable QTY	---	$W\leq 0.02$	Accept no dense	$L\leq 3.0$	$0.02 < W\leq 0.03$	2	$L\leq 2.5$	$0.03 < W\leq 0.05$	---	$0.05 < W$
Length	Width	Acceptable QTY													
---	$W\leq 0.02$	Accept no dense													
$L\leq 3.0$	$0.02 < W\leq 0.03$	2													
$L\leq 2.5$	$0.03 < W\leq 0.05$														
---	$0.05 < W$	As round type													
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. <table><tr><th>Size Φ</th><th>Acceptable QTY</th></tr><tr><td>$\Phi\leq 0.20$</td><td>Accept no dense</td></tr><tr><td>$0.20 < \Phi\leq 0.50$</td><td>3</td></tr><tr><td>$0.50 < \Phi\leq 1.00$</td><td>2</td></tr><tr><td>$1.00 < \Phi$</td><td>0</td></tr><tr><td>Total QTY</td><td>3</td></tr></table>	Size Φ	Acceptable QTY	$\Phi\leq 0.20$	Accept no dense	$0.20 < \Phi\leq 0.50$	3	$0.50 < \Phi\leq 1.00$	2	$1.00 < \Phi$	0	Total QTY	3	2.5
Size Φ	Acceptable QTY														
$\Phi\leq 0.20$	Accept no dense														
$0.20 < \Phi\leq 0.50$	3														
$0.50 < \Phi\leq 1.00$	2														
$1.00 < \Phi$	0														
Total QTY	3														



NO	Item	Criterion	AQL																		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination																			
06	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:  <table><tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr><tr><td>$Z \leq 1/2t$</td><td>Not over viewing area</td><td>$x \leq 1/8a$</td></tr><tr><td>$1/2t < z \leq 2t$</td><td>Not exceed $1/3k$</td><td>$x \leq 1/8a$</td></tr></table> ⊙ If there are 2 or more chips, x is total length of each chip. 6.1.2 Corner crack:  <table><tr><th>z: Chip thickness</th><th>y: Chip width</th><th>x: Chip length</th></tr><tr><td>$Z \leq 1/2t$</td><td>Not over viewing area</td><td>$x \leq 1/8a$</td></tr><tr><td>$1/2t < z \leq 2t$</td><td>Not exceed $1/3k$</td><td>$x \leq 1/8a$</td></tr></table> ⊙ If there are 2 or more chips, x is the total length of each chip.	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed $1/3k$	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed $1/3k$	$x \leq 1/8a$	2.5
		z: Chip thickness	y: Chip width	x: Chip length																	
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed $1/3k$	$x \leq 1/8a$																			
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed $1/3k$	$x \leq 1/8a$																			

NO	Item	Criterion	AQL																
06	Glass crack	Symbols : x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal : 6.2.1 Chip on electrode pad :  <table> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> 6.2.2 Non-conductive portion:  <table> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack.  <table> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$x \leq a$</td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$x \leq a$	2.5
		y: Chip width	x: Chip length	z: Chip thickness															
		$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$															
		y: Chip width	x: Chip length	z: Chip thickness															
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$x \leq a$																		

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB、COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  $X * Y \leq 2\text{mm}^2$	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icide. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65

MIDAS
DISPLAYS

Precautions in use of LCD Modules

DESIGN • MANUFACTURE • SUPPLY

1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
2. Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
3. Don't disassemble the LCM.
4. Don't operate it above the absolute maximum rating.
5. Don't drop, bend or twist LCM.
6. Soldering: only to the I/O terminals.
7. Storage: please storage in anti-static electricity container and clean environment.
8. Midas have the right to change the passive components
(Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
9. Midas have the right to change the PCB Rev.



Material List of Components for RoHs

1. Midas hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2. Process for RoHS requirement :

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. : _____
Reflow : 250°C, 30 seconds Max. ;
Connector soldering wave or hand soldering : 320°C, 10 seconds max.
- (3) Temp. curve of reflow, max. Temp. : 235±5°C ;
Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

Recommendable storage

1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
2. Do not place the module near organics solvents or corrosive gases.
3. Do not crush, shake, or jolt the module